

Features

- Fast switching device
- Power Dissipation of 250mW
- Low reverse leakage
- High Stability and High Reliability

Mechanical Characteristics

- Package: SOD-323
- Terminals: Plated solderable per MIL-STD-750, method 2026
- Mounting Position: Any
- Tape Reel :3000pcs

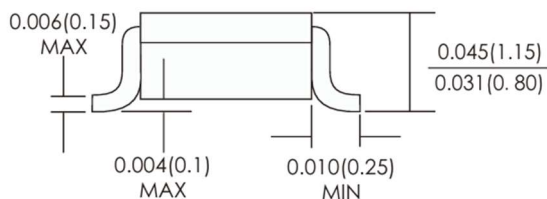
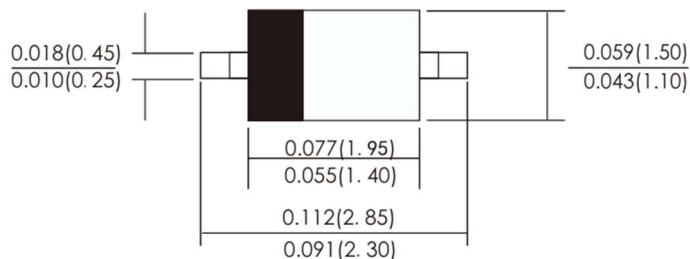
Applications

- Electronic computer
- Pulse
- Switching circuit

Marking information

- Marking: A6

SOD-323



Dimensions in inches and (millimeters)

Absolute Maximum Ratings (T=25°C, unless otherwise noted)

Parameter	Symbol	Value	Unit
Repetitive peak reverse voltage	V_{RRM}	100	V
Continuous reverse voltage	V_R	100	V
Average rectified output current	I_o	250	mA
Non-repetitive Peak Forward Surge Current @tp=1μs	I_{FSM}	2	A
Power Dissipation	P_D	250	mW
Operating Junction Temperature	T_J	150	°C
Storage Temperature	T_{STG}	-55 ~ +150	°C
Thermal Resistance Junction to Ambient	$R_{\theta JA}$	500	°C/W

Electrical Characteristics (T=25°C, unless otherwise noted)

Parameter	Symbol	Test Condition	Min	Max	Unit
Reverse Breakdown Voltage	$V_{(BR)R}$	$I_R = 100\mu A$	100		V
Reverse Leakage Current	I_R	$V_R = 25V$		30	nA
		$V_R = 75V$		1	μA
Forward Voltage	V_F	$I_F = 1.0mA$		0.715	V
		$I_F = 10mA$		0.855	
		$I_F = 50mA$		1	
		$I_F = 150mA$		1.25	
Total Capacitance	C_T	$V_R = 0V, f=1.0MHZ$		1.5	pF
Reverse Recovery Time	t_{rr}	$I_R = I_F = 10mA,$ $I_{RR} = 1mA, R_L = 100\Omega$		4	nS

Typical Characteristics

